

Serial Nr.: 09/627,979
Art Unit: 2814

UPA-00156

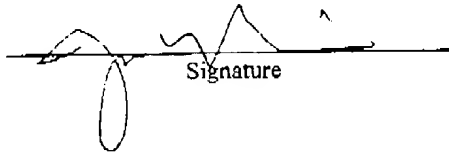
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: **09/627,979** Examiner: **DiLinh Nguyen**
Inventor: **Randy H. Y. Lo, Chi-Chuan Wu and Ssu-Cheng Lai**
Filed: **June 24, 2000** Art Unit: **2814**
Title: **Method Of Packaging Multi Chip Module**

Certificate of Transmission under 37 CFR 1.8

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Signature

Commissioner for Patents
Washington, D.C. 20231

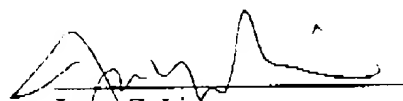
Sir:

AUG 18 2002

The following documents are facsimile transmitted herewith:

1. A Request for Continued Examination Transmittal;
2. Amendment B and Remarks (8 pages); and
3. A Credit Card Payment Form PTO-2038.

Respectfully submitted,


Jason Z. Lin
Agent for Applicants
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PTO/SB/30 (10-01)

Approved for use through 10/31/2002. OMB 0651-0031
U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

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REQUEST FOR CONTINUED EXAMINATION (RCE) TRANSMITTAL

Address to:
Commissioner for Patents
Box RCE
Washington, DC 20231

Application Number	09/627,979
Filing Date	June 24, 2000
First Named Inventor	Randy H. Y. Lo
Art Unit	2814
Examiner Name	DiLinh Nguyen
Attorney Docket Number	UPA-00156

This is a Request for Continued Examination (RCE) under 37 CFR 1.114 of the above-identified application. Request for Continued Examination (RCE) practice under 37 CFR 1.114 does not apply to any utility or plant application filed prior to June 8, 1995, or to any design application. See Instruction Sheet for RCEs (not to be submitted to the USPTO) on page 2.

1. Submission required under 37 CFR 1.114

- a. ☐ Previously submitted
- i. ☐ Consider the amendment(s)/reply under 37 CFR 1.116 previously filed on _____
(Any unentered amendment(s) referred to above will be entered).
- ii. ☐ Consider the arguments in the Appeal Brief or Reply Brief previously filed on _____
- iii. ☐ Other _____
- b. ☒ Enclosed
- i. ☒ Amendment/Reply
- ii. ☐ Affidavit(s)/Declaration(s)
- iii. ☐ Information Disclosure Statement (IDS)
- iv. ☐ Other _____

2. Miscellaneous

- a. ☐ Suspension of action on the above-identified application is requested under 37 CFR 1.103(c) for a period of _____ months. (Period of suspension shall not exceed 3 months; Fee under 37 CFR 1.17(i) required)
- b. ☐ Other _____

3. Fees

The RCE fee under 37 CFR 1.17(e) is required by 37 CFR 1.114 when the RCE is filed.

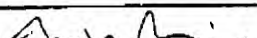
- a. ☐ The Director is hereby authorized to charge the following fees, or credit any overpayments, to Deposit Account No. _____
- i. ☐ RCE fee required under 37 CFR 1.17(e)
- ii. ☐ Extension of time fee (37 CFR 1.136 and 1.17)
- iii. ☐ Other _____

- b. ☐ Check in the amount of \$ _____ enclosed

- c. ☒ Payment by credit card (Form PTO-2038 enclosed)


WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.

SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT REQUIRED

Name (Print/Type)	Jason Z. Lin	Registration No. (Attorney/Agent)	37,492
Signature		Date	Aug. 18, 2002

CERTIFICATE OF MAILING OR TRANSMISSION

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner For Patents, Box RCE, Washington, DC 20231, or facsimile transmitted to the U.S. Patent and Trademark Office on the date shown below.

Name (Print/Type)	Jason Z. Lin	Date	Aug. 18, 2002
Signature			

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Serial No.: 09/627,979 Examiner: DiLinh Nguyen
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Commissioner for Patents
Washington, D.C. 20231

Sir:

AUG 18 2002

AMENDMENT B

In response to the Office Action mailed 05/23/2002, please amend the above-identified application as follows:

CLAIMS:

Cancel claims 46 and 55 and amend claims 41 and 49 as follows:

41. (Amended) A multi-chip module package structure comprising:

a substrate;

at least two chip packages, each of said chip packages being a packaged chip module having a bare chip packaged and embedded therein, burn-in tested and function tested;